

2018 EOS/ESD Manufacturing Symposium in Germany



November 6-7, Tutorials

**November 8-9, Manufacturing Symposium
and Exhibition**



ESD FORUM e.V.

The German ESD FORUM e.V. and the EOS/ESD Association, Inc. are working together to present the 3rd European EOS/ESD Manufacturing Symposium in Dresden, Germany. The collaboration between both organizations focuses on ESD protection issues during handling, assembly, and transport. Submit your presentation today!

Call for Presentations

Abstract Submission Deadline: June 4th, 2018

Submission Instructions

Your abstract (two pages including reasonably sized figures) must clearly present the data and the significance of the results. Please email your presentation abstract including title, author affiliation, and email address to info@esda.org by the Monday, June 4th, 2018 deadline. The submission format is a PDF® file (Adobe Acrobat®). Notification of acceptance will occur by August 24th, 2018.

Final, full presentations for the EOS/ESD Manufacturing Symposium in MS PowerPoint® format must be received by September 14th, 2018. These slides will be included in the presentation handout that will be distributed during the Symposium. There will be no published proceedings of the Symposium.

Technical papers that have been previously published may be considered. For questions please contact the Technical Program Chair: Rainer Pfeifle at rainer.pfeifle@warmbier.com.

Please visit the ESDA website at www.esda.org or the ESD FORUM e.V. website at www.esdforum.de for regular updates on the Symposium. As it becomes available, we will post information on the full technical program including seminars, technical sessions, and exhibits. Visit the web pages for information on the EOS/ESD Manufacturing Symposium registration, Dresden, Germany, and the surrounding area.

Abstract Submission Topics:

I. EOS/ESD Factory Level and Materials Technology

- Packaging and Handling
- Case Studies, Reviews and Analysis
- Test Methods and Procedures
- Troubleshooting Techniques
- Air Ionization and Uses
- Facility Design
- ESD Shunting Packaging Technology
- ESD Control Materials
- ESD Detection and Measurement Techniques
- Management Issues (cost/benefit analysis etc.)
- ESD Process Risk Assessment
- EMI Controls
- AHE Issues and Controls

II. EOS/ESD Standards – Components, System, Factory & Materials

- Test Methods and Procedures
- Standards – Comparisons and Analysis
- Case Studies
- Round-Robin Testing, Results and Analysis

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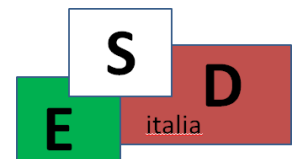
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